



**LTM8021 35LD 11.25mm X 6.25mm X 2.82mm (TABLE OF MATERIAL DECLARATION)**

*The LTM8021 is RoHS compliant per EU RoHS Directive 2003/95/EC.*

**It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)**

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.0604	Barium Compounds	7727-43-7	0.00091	1.5000
				Filler Substances (Silica Crystalline)	-	0.02412	39.9146
				Copper Metal	7440-50-8	0.03384	56.0000
				Copper Compounds	1328-53-6	0.00001	0.0180
				Ecotoxic substances	7439-92-1	0.00000	0.0004
				Gold metal or alloy	7440-57-5	0.00028	0.4600
				Nickel	7440-02-0	0.00127	2.1000
				Zinc	7440-66-6	0.00000	0.0070
2	Solder Paste	Alloy	0.0043	Sn	7440-31-5	0.00409	95.0000
				Sb	7440-36-0	0.00022	5.0000
3	Passive/Active Components		0.1214	Capacitor	-	0.02932	24.1451
				Resistor	-	0.00015	0.1211
				Inductor	-	0.09195	75.7313
				Diode	-	0.00000	0.0000
4	Active Ics	Silicon	0.0008	Silicon	7440-21-3	0.00079	100.0000
5	Wire	Gold	0.0002	Au	7440-57-5	0.00020	99.9900
6	Encapsulation	Epoxy Resin	0.3043	Fused Silica	60676-86-0	0.23492	77.2000
				Epoxy Resin	-	0.02708	8.9000
				Phenol Resin	-	0.02708	8.9000
				Crytalline Silica	14808-60-7	0.00913	3.0000
				Carbon Black	1333-86-4	0.00152	0.5000
				Metal Hydroxide	-	0.00456	1.5000
Total Package Weight			0.4914				

Note: Composition derived from MSDS and material C of C from Vendors

Component Weight based on assembly of generic parts